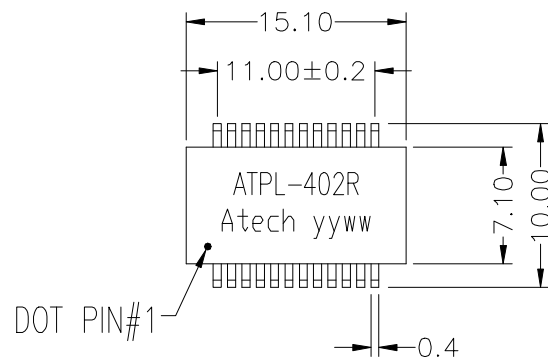
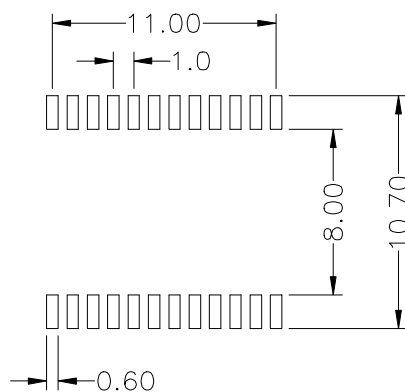
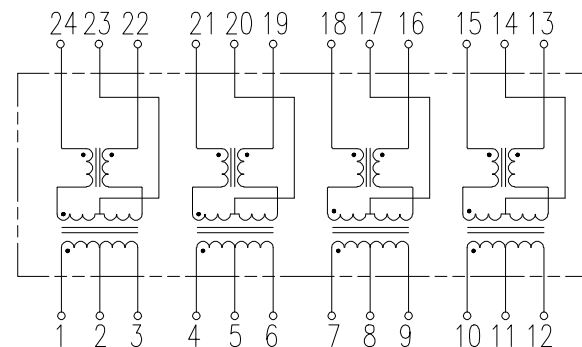


UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE ± 0.25



PCB SUGGEST PAD LAYOUT



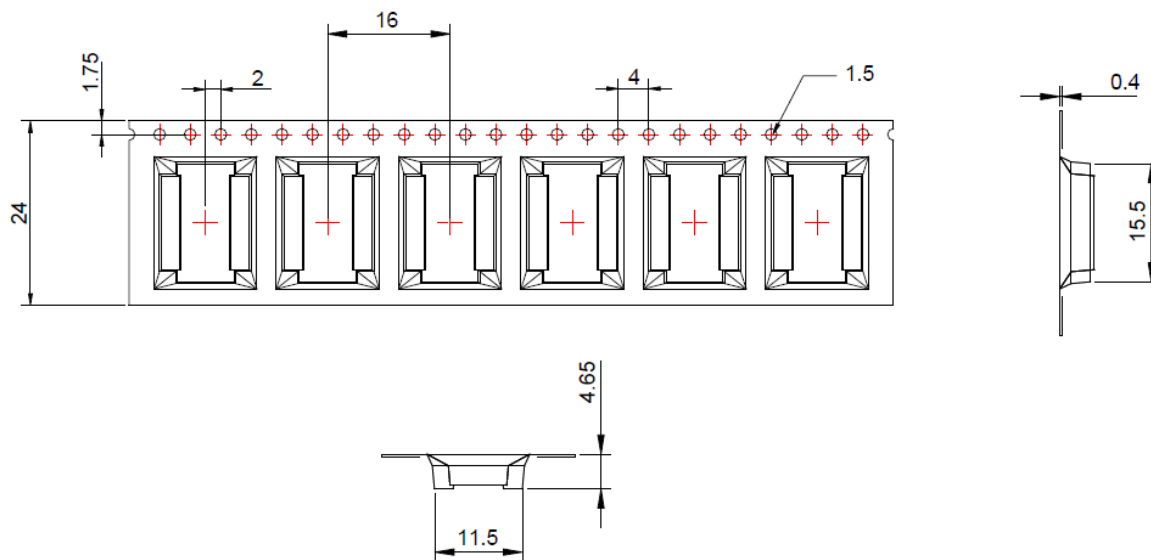
ELECTRICAL SPECIFICATIONS @25°C :

1. OCL : 350uH MIN. @100KHz, 0.1Vrms 8mA DC BIAS
2. TURN RATIO : TX = 1CT : 1CT
RX = 1CT : 1CT
3. VOLTAGE ISOLATION : 1500Vrms, 2mA, 60SEC
4. INSERTION LOSS : 1-100MHz = -1.1dB MAX.
5. RETURN LOSS (@100Ω) : 1-30MHz = -18dB MIN.
40MHz = -14.4dB MIN.
50MHz = -13.1dB MIN.
60-80MHz = -12dB MIN.
100MHz = -10dB MIN.
6. CROSS TALK : 1-100MHz = -30dB MIN.
7. DIFFERENTIAL TO COMMON MODE REJECTION :
1-100MHz = -30dB MIN.
8. INTERWINDING CAPACITANCE : 28PF Typ
9. DCR : 1.2Ω MAX.
10. LEAKAGE INDUCTANCE : 0.5uH MAX.
11. Compliant with IEEE 802.3at standard
12. RoHS COMPLIANT

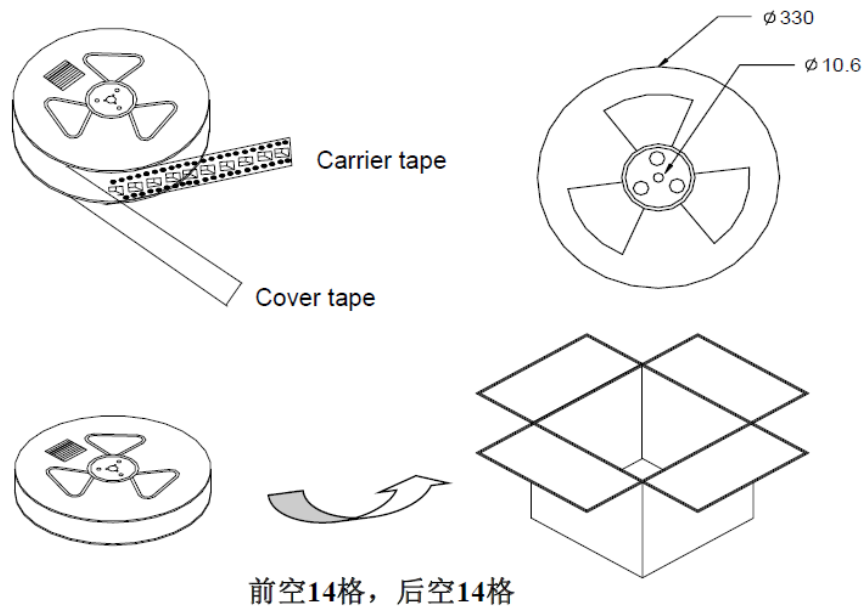
								TITLE 10/100/1000 BASE-PoE + TRANSFORMER	
								DWG. NO. ATPL-402R	
	RELEASE	05/30/2012	SHIRLEY	BETTY	BETTY	UNITS: M/M		SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE 05/30/12		P/N:	
REVISIONS						05/30/12		DRAW SHIRLEY	
								SHEET 1 of 1	

3. Package :

CARRIER TAPE



PACKAGE



Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 24 PIN Series	800	800x7=5600		0.8

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmmax)	150°C	200°C
Time (Tsmmin to Tsmmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max